

KLT-E6K-IMX214 V5.4 NLH

**13MP Sony IMX214 MIPI Interface M12 Fixed Focus Camera Module
No Lens and Holder**



Front View



Back View

Specifications

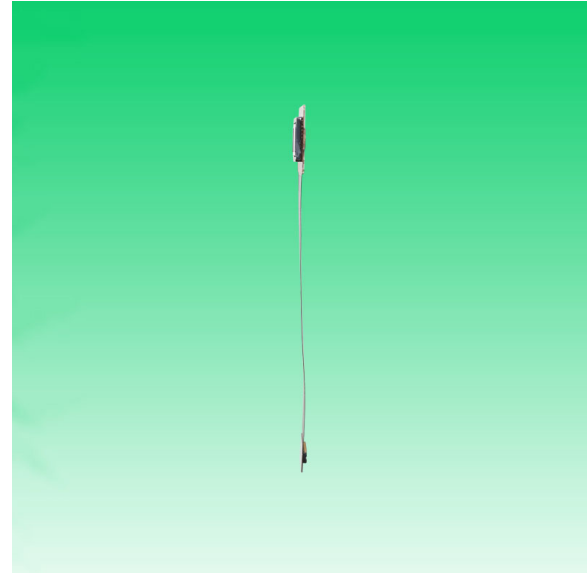
Camera Module No.	KLT-E6K-IMX214 V5.4 NLH
Resolution	13MP
Image Sensor	IMX214
Sensor Type	1/3.06"
Pixel Size	1.12 um x 1.12 um
Pixel	4224 x 3136
Module Size	74.00 x 22.00 mm
Module Type	Fixed Focus
Interface	MIPI
Auto Focus VCM Driver IC	None
Lens Type	No Lens and No Holder
Operating Temperature	-20°C to +70°C
Mating Connector	DF30FC-30DS-0.4V

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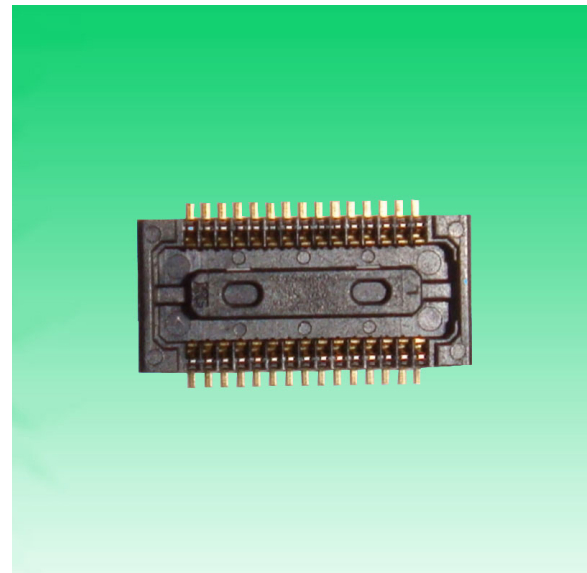
Top View



Side View



Bottom View

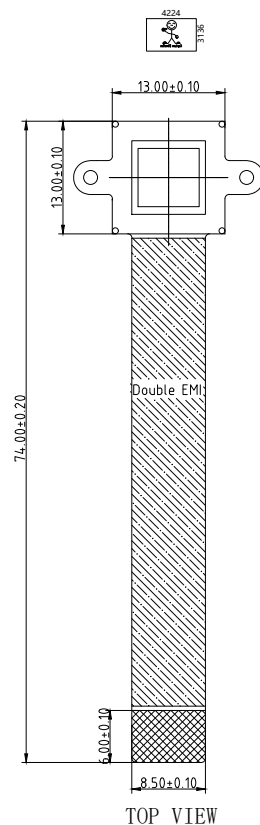


Mating Connector

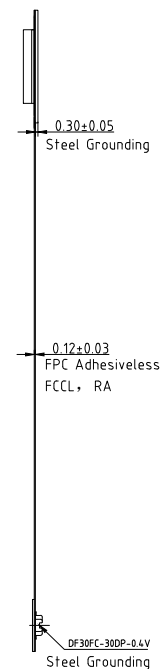
ROHS

PIN	SIGNAL
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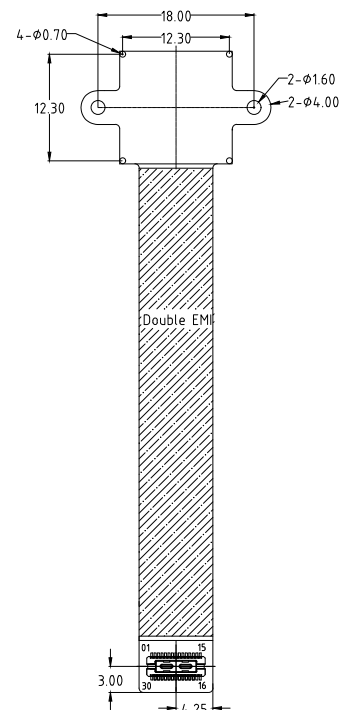
1	SID
2	NC
3	DVDD 1.0V
4	DOVDD 1.8V
5	NC
6	AGND
7	AVDD 2.8V
8	DGND
9	SDA
10	SCL
11	NC
12	PWDN
13	GND
14	MCLK
15	GND
16	MDP3
17	MDN3
18	GND
19	MDP2
20	MDN2
21	GND
22	MDP1
23	MDN1
24	GND
25	MCP
26	MCN
27	GND
28	MDP0
29	MDN0
30	GND



TOP VIEW



SIDE VIEW



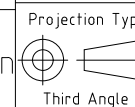
BOTTOM VIEW

Version	Information
V1.0	First Version
V2.0	Change lens and holder
V3.0	Remove lens and holder,Change capture direction
V4.0	Add PIN SID
V5.0	Change capture direction and FPC length
V5.2	Change FPC length and connector pin order
V5.4	Update layout

Kai Lap Technologies Group Ltd

Designed By Kevin Model Name: KLT-E6K-IMX214 V5.4 NLH

Checked By Aouly Yan



Projection Type: Third Angle

Unit: mm
Scale: 1:1

Date: 12/12/2024

Sheet: 1 of 1

Version: 1/0

NOTE:

1.Sensor I2C slave address:0x20 If SID=0;
or 0x34 If SID=1

[Product Brief]

Ver.1.0

IMX214

Diagonal 5.867mm (Type 1/3.06) 13M Pixel CMOS Image Sensor with Square Pixel for Color Cameras

Description

IMX214 is a diagonal 5.867mm (Type 1/3.06) 13M pixel CMOS active pixel type stacked image sensor with a square pixel array. It adopts Exmor RS™ technology to achieve high speed image capturing by column parallel A/D converter circuits and high sensitivity and low noise image (comparing with conventional CMOS image sensor) through the backside illuminated imaging pixel structure. R, G, and B pigment primary color mosaic filter is employed. By introducing spacially varying exposure technology, high dynamic range still pictures and movies are achievable. It equips an electronic shutter with variable integration time. It operates with three power supply voltages: analog 2.7 V, digital 1.0V and 1.8 V for input/output interface and achieves low power consumption. IMX214 is designed for use in cellular phones or tablet devices*.

Functions and Features

- ◆ Back illuminated and stacked CMOS image sensor Exmor RS
- ◆ Single Frame High Dynamic Range (HDR) with equivalent full pixels.
- ◆ High signal to noise ratio (SNR).
- ◆ Full resolution @30fps (Normal / HDR). 4K2K @30fps (Normal / HDR) 1080p @60fps (Normal / HDR)
- ◆ Output video format of RAW10/8, COMP8/6
- ◆ Pixel binning readout and H/V sub sampling function
- ◆ Advanced Noise Reduction (Chroma noise reduction and luminance noise reduction)
- ◆ Independent flipping and mirroring.
- ◆ CSI 2 serial data output (MIPI 2lane/4lane, Max. 1.2Gbps/lane, DPHY spec. ver. 1.1 compliant)
- ◆ 2wire serial communication
- ◆ Two PLLs for independent clock generation for pixel control and data output interface.
- ◆ Advanced Noise Reduction.
- ◆ Dynamic Defect Pixel Correction.
- ◆ Zero shutter lag.
- ◆ Power on reset function
- ◆ Dual sensor synchronization operation.
- ◆ 8K bit of OTP ROM for users.
- ◆ Built in temperature sensor

NOTE)

1. When using this product for another application, Sony does not guarantee the quality and reliability of product. Therefore, don't use this for applications other than cellular phone and Tablet PCs. Consult your Sony sales representative if you have any questions.

Device Structure

◆ CMOS image sensor	
◆ Image size	: Diagonal 5.867mm (Type 1/3.06)
◆ Total number of pixels	: 4224 (H) × 3200 (V) approx. 13.51M pixels
◆ Number of effective pixels	: 4224 (H) × 3136 (V) approx. 13.25 M pixels
◆ Number of active pixels	: 4208 (H) × 3120 (V) approx. 13.13 M pixels
◆ Chip size	: 6.100mm (H) × 4.524mm (V)
◆ Unit cell size	: 1.12 μm (H) × 1.12 μm (V)
◆ Substrate material	: Silicon

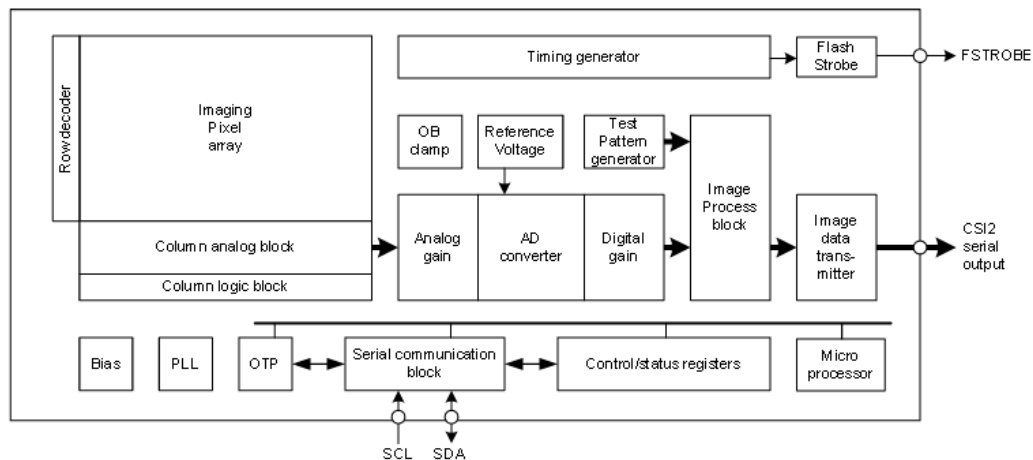
Functional Description

System Outline

IMX214 is a CMOS active pixel type image sensor which adopts the Exmor RS™ technology to achieve high sensitivity, low noise and high speed image capturing. It is embedded with backside illuminated imaging pixel, low noise analog amplifier, column parallel A/D converters which enables high speed capturing, digital amplifier, image binning circuit, timing control circuit for imaging size and frame rate, CSI2 image data high speed serial interface, PLL oscillator, and serial communication interface to control these functions.

Several additional image processing functions and peripheral circuits are also included for easy system optimization by the users. A one time programmable memory is embedded in the chip for storing the user data. It has 8 K-bit for users, 10 K-bit as a whole.

Block Diagram



Exmor RS

* Exmor RS is a trademark of Sony Corporation. The Exmor RS is a Sony's CMOS image sensor with high-resolution, high-performance and compact size by replacing a supporting substrate in Exmor R™ which changed fundamental structure of Exmor™ pixel adopted column parallel A/D converter to back-illuminated type, with layered chips formed signal processing circuits.

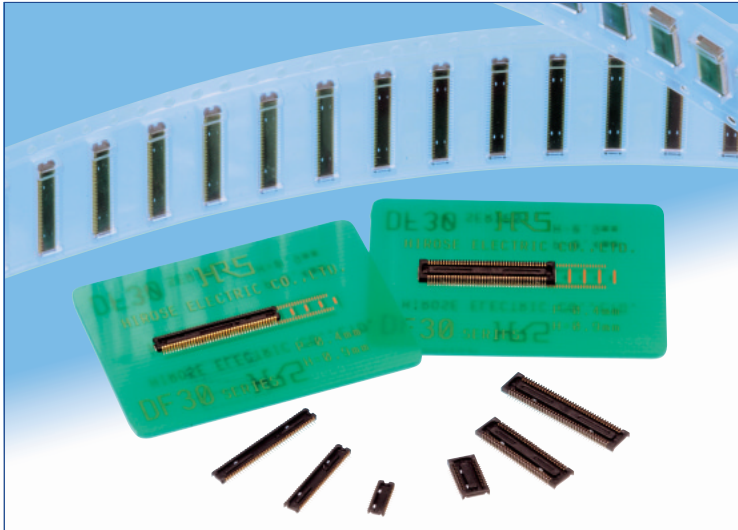
Sony reserves the right to change products and specifications without prior notice.

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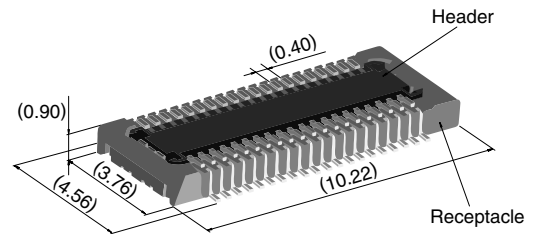
Application circuits shown, if any, are typical examples illustrating the operation of the devices. Sony cannot assume responsibility for any problems arising out of the use of these circuits.

0.4 mm Pitch, 0.9 mm Height, Board-to-Board / Board-to-FPC Connectors

DF30 Series



Extremely small size



40 positions shown

Overview

Continuous miniaturization and increased component density on PCB created demand for extremely low profile connectors. This series is addition of a new extremely low profile connectors to Hirose's wide range of high reliability board-to-board/board-to-FPC connection solutions.

Features

1. Contact reliability

Concentration of the contact's normal forces at the single point assures good contact wipe and electrical reliability, while confirming the fully mated condition with a definite tactile click.

2. Self alignment

Recognizing the difficulties of mating extremely small connectors in limited spaces the connectors will self align in horizontal axis within 0.3 mm.

3. Automatic board placement

Packaged on tape-and-reel the plug and headers have sufficiently large flat areas to allow pick-up with vacuum nozzles of automatic placement equipment.

4. Variety of contact positions and styles

Available in standard contact positions of: 20, 22, 24, 30, 34, 40, 50, 60, 70 and 80 with and without metal fittings. Addition of metal fittings does not affect external dimensions of the connectors.

Smaller contact positions are also available.

5. Support for continuity test connector

Connectors which have increased insertion and removal durability are available for continuity tests. Contact your Hirose sales representative for details.

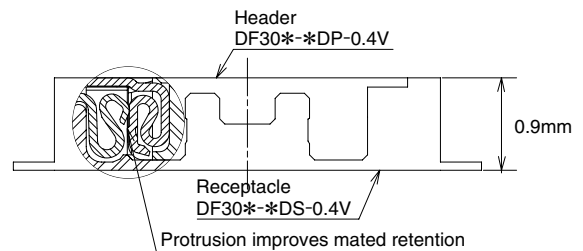
Applications

Cellular phones, PDA's, mobile computers, digital cameras, digital video cameras, and other devices demanding high reliability connections in extremely limited spaces.

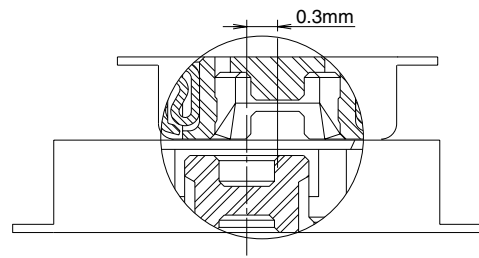
Low profile

Increased mated retention

High contact reliability



Self alignment



■Product Specifications

Rating	Rated current 0.3A Rated voltage 30V AC	Operating temperature range : -35℃ to 85℃ (Note 1) Operating humidity range : Relative humidity 20% to 80%	Storage temperature range -10℃ to 60℃ (Note 2) Storage humidity range Relative humidity 40% to 70% (Note 2)
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Item	Specification	Conditions
1. Insulation resistance	50 MΩ min.	100V DC
2. Withstanding voltage	No flashover or insulation breakdown.	100V AC / one minute
3. Contact resistance	100 mΩ max.	100 mA
4. Vibration	No electrical discontinuity of 1 μs or more	Frequency: 10 to 55 Hz, single amplitude of 0.75mm, 2 hours, 3 axis
5. Humidity	Contact resistance: 100 mΩ max. Insulation resistance: 25 MΩ min.	96 hours at temperature of 40℃±2℃ and RH of 90% to 95%
6. Temperature cycle	Contact resistance: 100 mΩ max. Insulation resistance: 50 MΩ min.	Temperature: -55℃→+5℃ to +35℃→+85℃→+5℃ to +35℃ Duration: 30→10→30→10(Minutes) 5 cycles
7. Durability (insertions/withdrawals)	Contact resistance: 100 mΩ max.	50 cycles(Connector for conductivity tests: 500 cycles)
8. Resistance to soldering heat	No deformation of components affecting performance.	Reflow: At the recommended temperature profile Manual soldering: 300℃ for 3 seconds

Note 1: Includes temperature rise caused by current flow.

Note 2: The term "storage" refers to products stored for long period of time prior to mounting and use. Operating temperature range and humidity range covers non-conducting condition of installed connectors in storage, shipment or during transportation.

■Materials and Finishes

Connectors	Component	Material	Finish	Remarks
Receptacles and Headers	Insulator	LCP	Color : Black	UL94V-0
	Contacts	Phosphor bronze	Gold plated	————
	Metal fittings	Phosphor bronze	Tin-copper plated	————

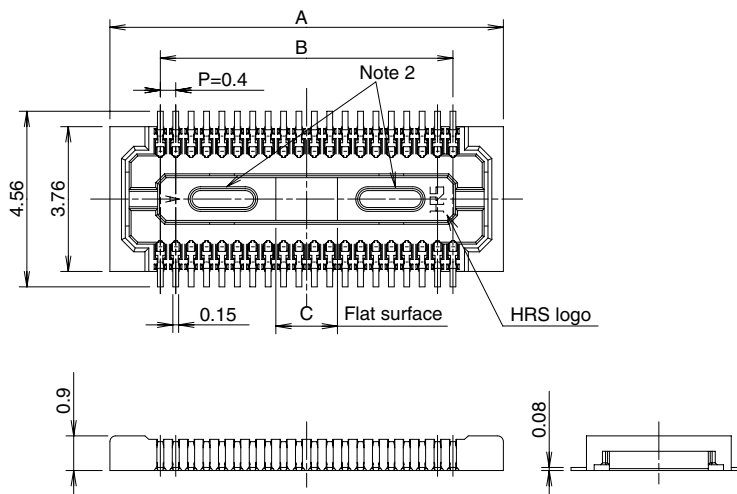
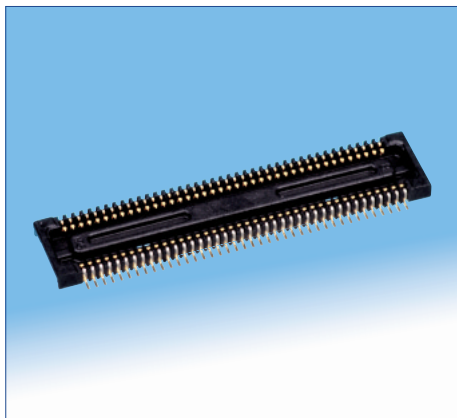
■Ordering information

●Receptacles and Headers

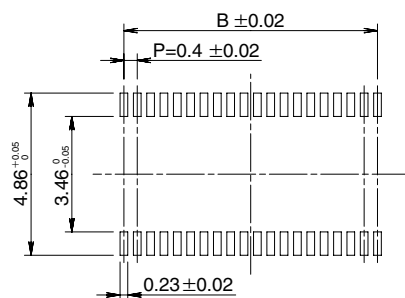
DF30 FC - * DS - 0.4 V (**)
 ① ② ③ ④ ⑤ ⑥ ⑦

① Series name: DF30	⑤ Contact pitch: 0.4 mm
② Configuration FB: With metal fittings, without bosses FC: Without metal fittings, without bosses CJ: Connector for conductivity tests	⑥ Termination section V: Straight SMT
③ Number of positions: 20, 22, 24, 30, 34, 40, 50, 60, 70, 80	⑦ Packaging (81): Embossed tape packaging (5,000 pieces per reel) (82): Embossed tape packaging (1,000 pieces per reel)
④ Connector type DS: Double row receptacle DP: Double row header	

■Receptacles (without metal fittings)



◆Recommended PCB mounting pattern



Recommended solder paste thickness: 120 μ m

[Specification number] -**, (**)

(81): Embossed tape packaging (5,000 pieces per reel)

* Tolerances non- accumulative.

Unit: mm

Part Number	CL No.	Number of contacts	A	B	C
DF30FC-20DS-0.4V(**)	CL684-1109-8-**-	20	6.22	3.6	1.2
DF30FC-22DS-0.4V(**)	CL684-1110-7-**-	22	6.62	4.0	1.2
DF30FC-24DS-0.4V(**)	CL684-1111-0-**-	24	7.02	4.4	1.2
DF30FC-30DS-0.4V(**)	CL684-1112-2-**-	30	8.22	5.6	1.2
DF30FC-34DS-0.4V(**)	CL684-1113-5-**-	34	9.02	6.4	1.36
DF30FC-40DS-0.4V(**)	CL684-1078-6-**-	40	10.22	7.6	1.6
DF30FC-50DS-0.4V(**)	CL684-1114-8-**-	50	12.22	9.6	2.0
DF30FC-60DS-0.4V(**)	CL684-1082-3-**-	60	14.22	11.6	2.4
DF30FC-70DS-0.4V(**)	CL684-1115-0-**-	70	16.22	13.6	2.8
DF30FC-80DS-0.4V(**)	CL684-1116-3-**-	80	18.22	15.6	3.2

Note 1: Order by number of reels.

Note 2: Receptacles with 24 or fewer contacts positions will not have recessed areas.

Cameras Applications



Automotive Driver Pilot



Live Streaming



Video Conference



Eye Tracker Biometric Detection



Machine Vision



Agricultural Monitor



Night Vision Security



Drone and Sports Eagle Eyes



Interactive Pet Camera



Cameras Applications

your BEST camera module partner



IMAGING DEVICES



Camera Module Pinout Definition Reference Chart

OmniVision Sony Samsung On-Semi Aptina Himax GalaxyCore PixArt SmartSens Sensors	
Pin Signal	Description
DGND GND	ground for digital circuit
AGND	ground for analog circuit
PCLK DCK	DVP PCLK output
XCLR PWDN XSHUTDOWN STANDBY	power down active high with internal pull-down resistor
MCLK XVCLK XCLK INCK	system input clock
RESET RST	reset active low with internal pull-up resistor
NC NULL	no connect
SDA SIO_D SIOD	SCCB data
SCL SIO_C SIOC	SCCB input clock
VSYNC XVS FSYNC	DVP VSYNC output
HREF XHS	DVP HREF output
DOVDD	power for I/O circuit
AFVDD	power for VCM circuit
AVDD	power for analog circuit
DVDD	power for digital circuit
STROBE FSTROBE	strobe output
FSIN	synchronize the VSYNC signal from the other sensor
SID	SCCB last bit ID input
ILPWM	mechanical shutter output indicator
FREX	frame exposure / mechanical shutter
GPIO	general purpose inputs
SLASEL	I2C slave address select
AFEN	CEN chip enable active high on VCM driver IC
MIPI Interface	
MDN0 DN0 MD0N DATA_N DMO1N	MIPI 1st data lane negative output
MDP0 DP0 MD0P DATA_P DMO1P	MIPI 1st data lane positive output
MDN1 DN1 MD1N DATA2_N DMO2N	MIPI 2nd data lane negative output
MDP1 DP1 MD1P DATA2_P DMO2P	MIPI 2nd data lane positive output
MDN2 DN2 MD2N DATA3_N DMO3N	MIPI 3rd data lane negative output
MDP2 DP2 MD2P DATA3_P DMO3P	MIPI 3rd data lane positive output
MDN3 DN3 MD3N DATA4_N DMO4N	MIPI 4th data lane negative output
MDP3 DP3 MD3P DATA4_P DMO4P	MIPI 4th data lane positive output
MCN CLKN CLK_N DCKN	MIPI clock negative output
MCP CLKP MCP CLK_P DCKN	MIPI clock positive output
DVP Parallel Interface	
D0 DO0 Y0	DVP data output port 0
D1 DO1 Y1	DVP data output port 1
D2 DO2 Y2	DVP data output port 2
D3 DO3 Y3	DVP data output port 3
D4 DO4 Y4	DVP data output port 4
D5 DO5 Y5	DVP data output port 5
D6 DO6 Y6	DVP data output port 6
D7 DO7 Y7	DVP data output port 7
D8 DO8 Y8	DVP data output port 8
D9 DO9 Y9	DVP data output port 9
D10 DO10 Y10	DVP data output port 10
D11 DO11 Y11	DVP data output port 11

Camera Reliability Test

Reliability Inspection Item			Testing Method	Acceptance Criteria
Category		Item		
Environmental	Storage Temperature	High 60°C 96 Hours	Temperature Chamber	No Abnormal Situation
		Low -20°C 96 Hours	Temperature Chamber	No Abnormal Situation
	Operation Temperature	High 60°C 24 Hours	Temperature Chamber	No Abnormal Situation
		Low -20°C 24 Hours	Temperature Chamber	No Abnormal Situation
	Humidity	60°C 80% 24 Hours	Temperature Chamber	No Abnormal Situation
	Thermal Shock	High 60°C 0.5 Hours Low -20°C 0.5 Hours Cycling in 24 Hours	Temperature Chamber	No Abnormal Situation
Physical	Drop Test (Free Falling)	Without Package 60cm	10 Times on Wood Floor	Electrically Functional
		With Package 60cm	10 Times on Wood Floor	Electrically Functional
	Vibration Test	50Hz X-Axis 2mm 30min	Vibration Table	Electrically Functional
		50Hz Y-Axis 2mm 30min	Vibration Table	Electrically Functional
		50Hz Z-Axis 2mm 30min	Vibration Table	Electrically Functional
	Cable Tensile Strength Test	Loading Weight 4 kg 60 Seconds Cycling in 24 Hours	Tensile Testing Machine	Electrically Functional
Electrical	ESD Test	Contact Discharge 2 KV	ESD Testing Machine	Electrically Functional
		Air Discharge 4 KV	ESD Testing Machine	Electrically Functional
	Aging Test	On/Off 30 Seconds Cycling in 24 Hours	Power Switch	Electrically Functional
	USB Connector	On/Off 250 Times	Plug and Unplug	Electrically Functional



Inspection Item		Inspection Method	Standard of Inspection	
Category	Item			
Appearance	FPC/ PCB	Color	The Naked Eye	Major Difference is Not Allowed.
		Be Torn/Chopped	The Naked Eye	Copper Crack Exposure is Not Allowed.
		Marking	The Naked Eye	Clear, Recognizable (Within 30cm Distance)
	Holder	Scratches	The Naked Eye	The Inside Crack Exposure is Not Allowed
		Gap	The Naked Eye	Meet the Height Standard
		Screw	The Naked Eye	Make Sure Screws Are Presented (If Any)
		Damage	The Naked Eye	The Inside Crack Exposure is Not Allowed
	Lens	Scratch	The Naked Eye	No Effect On Resolution Standard
		Contamination	The Naked Eye	No Effect On Resolution Standard
		Oil Film	The Naked Eye	No Effect On Resolution Standard
		Cover Tape	The Naked Eye	No Issue On Appearance.
	Function	Image	No Communication	Test Board
Bright Pixel			Black Board	Not Allowed In the Image Center
Dark Pixel			White board	Not Allowed In the Image Center
Blurry			The Naked Eye	Not Allowed
No Image			The Naked Eye	Not Allowed
Vertical Line			The Naked Eye	Not Allowed
Horizontal Line			The Naked Eye	Not Allowed
Light Leakage			The Naked Eye	Not Allowed
Blinking Image			The Naked Eye	Not Allowed
Bruise			Inspection Jig	Not Allowed
Resolution			Chart	Follows Outgoing Inspection Chart Standard
Color			The Naked Eye	No Issue
Noise			The Naked Eye	Not Allowed
Corner Dark			The Naked Eye	Less Than 100px By 100px
Color Resolution			The Naked Eye	No Issue
Dimension			Height	The Naked Eye
		Width	The Naked Eye	Follows Approval Data Sheet
		Length	The Naked Eye	Follows Approval Data Sheet
		Overall	The Naked Eye	Follows Approval Data Sheet

KLT Package Solutions

KLT Camera Module



Complete with Lens Protection Film



Tray with Grid and Space



Place Cameras on the Tray



Camera Modules Package Solution

Full Tray of Cameras



Cover Tray with Lid



Put Tray into Anti-Static Bag



Vacuum the Anti-Static Bag



Camera Modules Package Solution

Sealed Vacuum Bag with Labels

1. Model and Description 2. Quantity 3. Shipping Date 4. Caution



Large Order Package Solution

Place Foam Sheets Between Trays



Foam Sheets are Slightly Larger than Trays



Place Foam Sheets and Trays into Box



Foam Sheets are Tightly Fitting Box



Small Order Package Solution

Place Foam Sheets and Trays into Small Box



Foam Sheets are Nicely Fitting the Small Box



Package in Small Box for Shipment



Place Small Boxes into Larger Box



Carbon Box Package Solution

Seal the Carbon Box

Final Package Labelled Box



Carbon Box Ready for Shipment

1. Delivery Address and Phone No. 2. Box No. and Ship Date 3. Fragile Caution



Sample Order Package Solution

Place Sample into Small Anti-Static Bag



Place Connectors into Small Ant-Static Bag



Sample Labels on the Small Bag

1. Camera Module or Connector Model 2. Shipping Date and Quantity 3. Caution



Connectors Large Order Package Solution

Connectors in a Wheel



Label Connectors in the Wheel



The Wheel is Perfectly Fitting the Box



Connectors Box Ready for Shipment





CMOS CAMERA MODULES



your BEST camera module partner

Company Kai Lap Technologies (KLT)

Kai Lap Technologies Group Limited. (KLT) was established in 2009, a next-generation technology driven manufacturer specialized in research, design, and produce of audio and video products. KLT is occupying 20,000 square feet automated plants with 100 employees of annual throughput 30,000,000 units cameras.

KLT provides OEM, ODM design, contract manufacturing, and builds the camera products. You may provide the requirements to us, even with a hand draft, our sales and engineering work together to meet your needs. We consider ourselves your last-term partner in developing practical and innovative solutions.

Our team covers everything from initial concept development to mass produced product. KLT specializes in customized camera design, raw material, electronic engineering, firmware/software development, product testing, and packing design. Our experienced strategic supply systems offer a robust and dependable manufacturing capacity for orders of various sizes.



Limited Warranty

KLT provides the following limited warranty if you purchased the Product(s) directly from KLT company or from KLT's website, www.KaiLapTech.com. Product(s) purchased from other sellers or sources are not covered by this Limited Warranty. KLT guarantees that the Product(s) will be free from defects in materials and workmanship under normal use for a period of one (1) year from the date you receive the product ("Warranty Period").

For all Product(s) that contain or develop material defects in materials or workmanship during the Warranty Period, KLT will, at its sole option, either: (i) repair the Product(s); (ii) replace the Product(s) with a new or refurbished Product(s) (replacement Product(s) being of identical model or functional equivalent); or (iii) provide you a refund of the price you paid for the Product(s).

This Limited Warranty of KLT is solely limited to repair and/or replacement on the terms set forth above. KLT is not reliable or responsible for any subsequent events.



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CMOS CAMERA MODULES



your BEST camera module partner

KLT Strength

Powerful Factory



Professional Service



Promised Delivery



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